

## PATENT ABSTRACTS OF JAPAN

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(71)Applicant : SEKISUI CHEM CO LTD

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(72)Inventor : NIKI AKIHIRO

HYOZU SHUNJI

MAKINO KOZO

### (54) THERMALLY CONDUCTIVE RESIN SHEET

#### (57)Abstract:

**PROBLEM TO BE SOLVED:** To obtain a thermally conductive sheet exhibiting high thermal conductivity and excellent in flexibility, mechanical strength and adhesion to a part to which it is applied.

**SOLUTION:** The thermally conductive resin sheet comprises a foam which comprises a soft resin and a thermally conductive filler and is expanded to the extent that it has an expansion ratio within the range of 1.1 to 5.0 times. The soft resin is preferably an acrylic resin. Furthermore, the thermally conductive filler preferably accounts for 5-90 vol.% of the thermally conductive resin sheet. As examples thereof, there can be mentioned metal oxides, metals and the like.